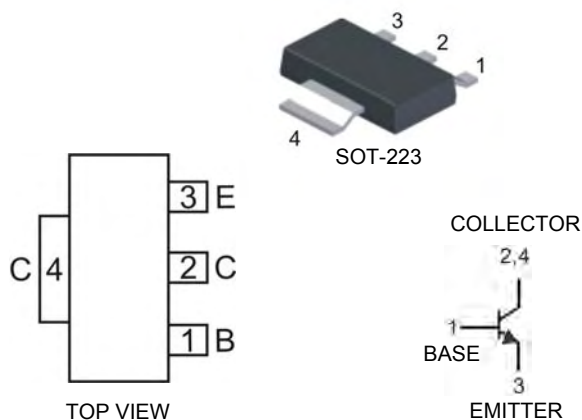


Features

- Epitaxial Planar Die Construction
- Ideally Suited for Automated Assembly Processes
- Ideal for Medium Power Switching or Amplification Applications
- **Lead Free By Design/RoHS Compliant (Note 1)**
- **"Green" Device (Note 2)**

Mechanical Data

- Case: SOT-223
- Case Material: Molded Plastic, "Green" Molding Compound.
UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminals: Finish — Matte Tin annealed over Copper Leadframe
(Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 3
- Ordering Information: See Page 3
- Weight: 0.115 grams (approximate)



Schematic and Pin Configuration

Maximum Ratings @T_A = 25°C unless otherwise specified

| Characteristic | Symbol | Value | Unit |
|---|-----------------------------------|-------------------------------|------|
| Collector-Base Voltage | V _{CBO} | 50 | V |
| Collector-Emitter Voltage | V _{CEO} | 25 | V |
| Emitter-Base Voltage | V _{EBO} | 7.0 | V |
| Collector Current | I _C | 5.0 | A |
| Base Current | I _B | 1.0 | A |
| Power Dissipation | P _D | 1 (Note 3) 2 (Note 4) | W |
| Thermal Resistance, Junction-to-Ambient | R _{θJA} | 125 (Note 3) 62.5 (Note 4) | °C/W |
| Operating and Storage Temperature Range | T _J , T _{STG} | -65 to +150 | °C |

- Notes:
1. No purposefully added lead.
 2. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
 3. Device mounted on FR-4 PCB, pad layout as shown on page 4.
 4. Device mounted on Polyimide PCB with a copper area of 1.8cm².

Electrical Characteristics @T_A = 25°C unless otherwise specified

| Characteristic | Symbol | Min | Typ | Max | Unit | Test Condition |
|--------------------------------------|----------------------|------------------|-----|---------------|--------|---|
| OFF CHARACTERISTICS | | | | | | |
| Collector-Emitter Breakdown Voltage | V _{(BR)CEO} | 25 | — | — | V | I _C = 10mA, I _B = 0 |
| Collector Cutoff Current | I _{CBO} | — | — | 1.0 | μA | V _{CB} = 50V, I _E = 0 |
| Emitter Cutoff Current | I _{EBO} | — | — | 1.0 | μA | V _{EB} = 7.0V, I _C = 0 |
| ON CHARACTERISTICS | | | | | | |
| Collector-Emitter Saturation Voltage | V _{CE(SAT)} | — | — | 0.35 0.50 | V V | I _C = 3.0A, I _B = 150mA* I _C = 4.0A, I _B = 200mA* |
| Base-Emitter Saturation Voltage | V _{BE(SAT)} | — | — | 1.10 1.40 | V V | I _C = 3.0A, I _B = 150mA* I _C = 4.0A, I _B = 200mA* |
| DC Current Gain | h _{FE} | 250 150 50 | — | 500 — — | — | I _C = 500mA, V _{CE} = 2.0V* I _C = 2.0A, V _{CE} = 2.0V* I _C = 5.0A, V _{CE} = 2.0V* |
| SMALL SIGNAL CHARACTERISTICS | | | | | | |
| Current Gain-Bandwidth Product | f _T | — | 150 | — | MHz | I _C = 50mA, V _{CE} = 6.0V, f = 200MHz |
| Output Capacitance | C _{obo} | — | — | 50 | pF | V _{CB} = 10V, I _E = 0, f = 1MHz |

* Measured under pulsed conditions. Pulse width = 300μs. Duty cycle ≤2%

Typical Characteristics @T_{amb} = 25°C unless otherwise specified

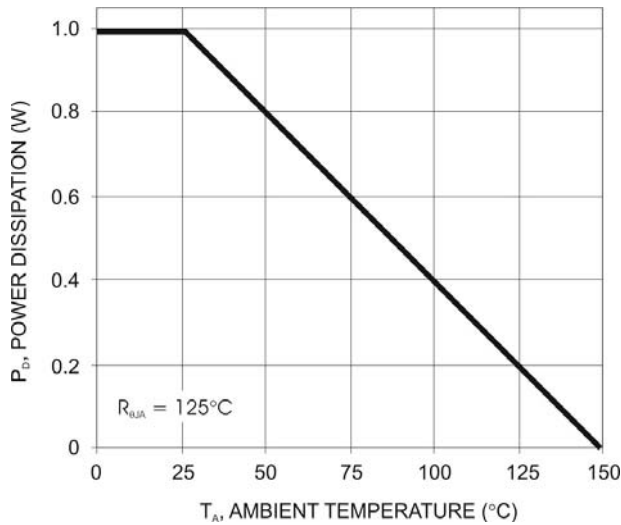


Fig. 1 Power Dissipation vs. Ambient Temperature (Note 3)

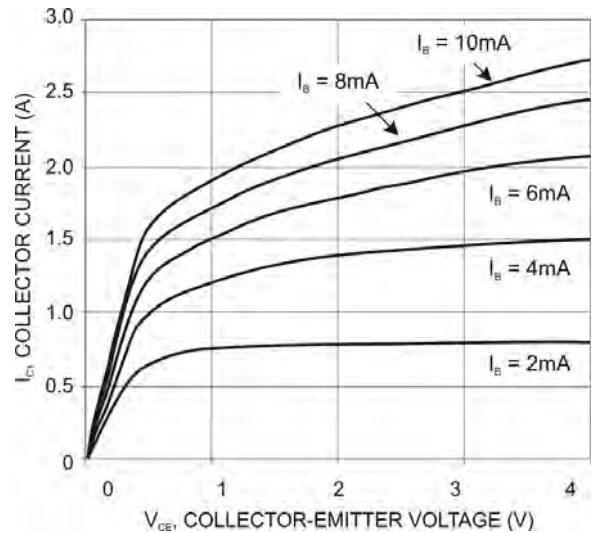


Fig. 2 Collector Current vs. Collector Emitter-Voltage

Notes: 3. Device mounted on FR-4 PCB, pad layout as shown on page 4.

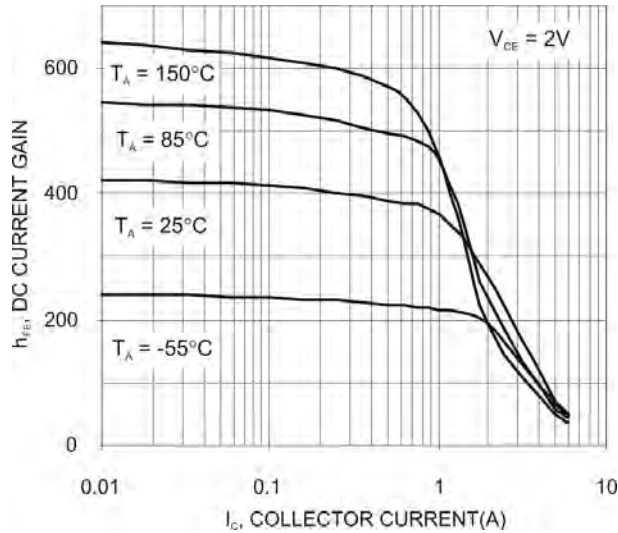


Fig. 3 Typical DC Current Gain vs. Collector Current

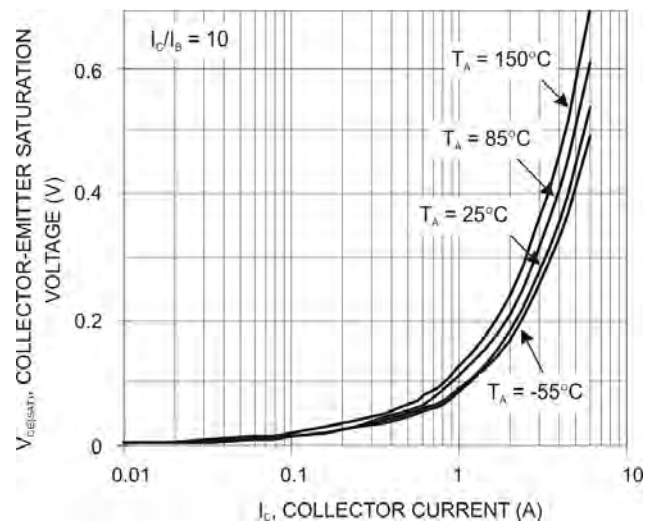


Fig. 4 Collector-Emitter Saturation Voltage vs. Collector Current

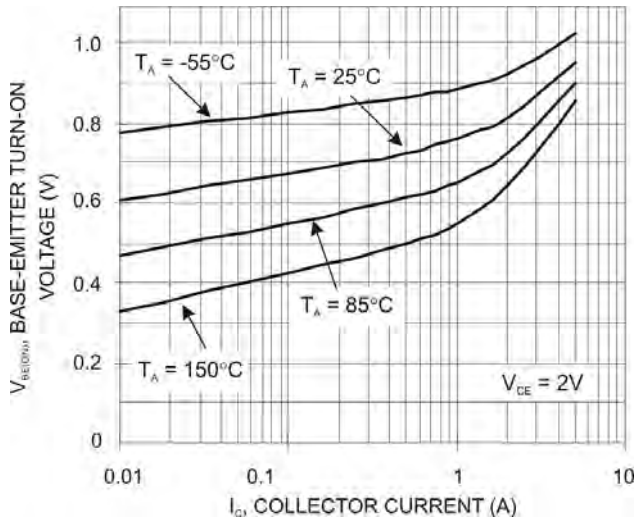


Fig. 5 Base-Emitter Turn-On Voltage vs. Collector Current

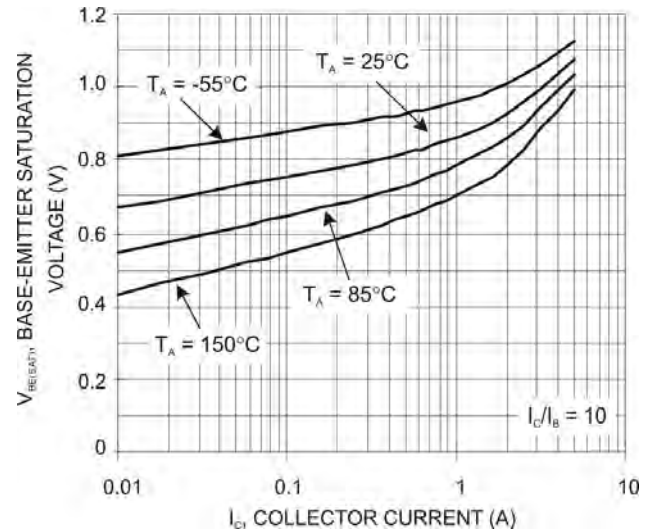


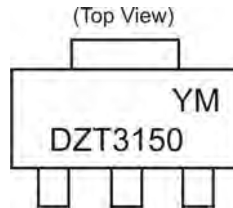
Fig. 6 Base-Emitter Saturation Voltage vs. Collector Current

Ordering Information (Note 5)

| Device | Packaging | Shipping |
|------------|-----------|------------------|
| DZT3150-13 | SOT-223 | 2500/Tape & Reel |

Notes: 5. Packaging Details as shown on page 4, or go to our website at <http://www.diodes.com/ap2007.pdf>.

Marking Information



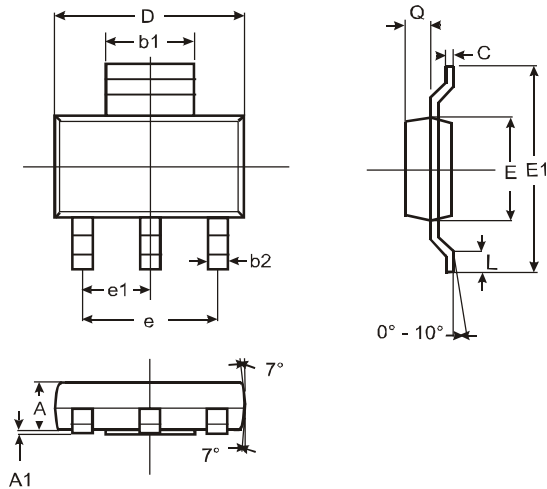
DZT3150 = Product Type Marking Code
 YM = Date Code Marking
 Y = Year ex: T = 2006
 M = Month ex: 9 = September

Date Code Key

| Year | 2006 | 2007 | 2008 | 2009 | 2010 | 2011 | 2012 |
|------|------|------|------|------|------|------|------|
| Code | T | U | V | W | X | Y | Z |

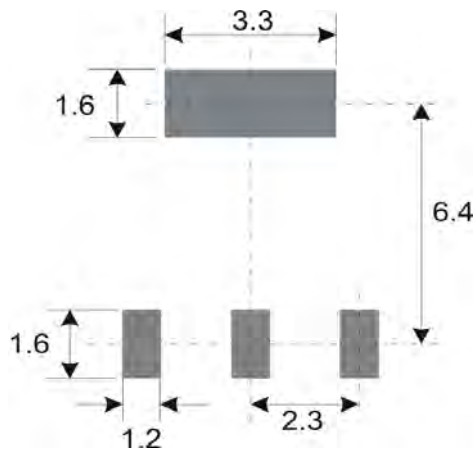
| Month | Jan | Feb | Mar | Apr | May | Jun | Jul | Aug | Sep | Oct | Nov | Dec |
|-------|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|
| Code | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | O | N | D |

Package Outline Dimensions



| SOT-223 | | | |
|----------------------|-------|------|------|
| Dim | Min | Max | Typ |
| A | 1.55 | 1.65 | 1.60 |
| A1 | 0.010 | 0.15 | 0.05 |
| b1 | 2.90 | 3.10 | 3.00 |
| b2 | 0.60 | 0.80 | 0.70 |
| C | 0.20 | 0.30 | 0.25 |
| D | 6.45 | 6.55 | 6.50 |
| E | 3.45 | 3.55 | 3.50 |
| E1 | 6.90 | 7.10 | 7.00 |
| e | — | — | 4.60 |
| e1 | — | — | 2.30 |
| L | 0.85 | 1.05 | 0.95 |
| Q | 0.84 | 0.94 | 0.89 |
| All Dimensions in mm | | | |

Suggested Pad Layout: (Based on IPC-SM-782)



(Unit:mm)

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